

AMENDMENTS TO THE CLAIMS

1. (Previously presented) A method for forming a solder resist pattern comprising the steps of:

pre-treating both sides of a double-sided printed circuit board, wherein pre-treating includes scrubbing;

laminating a semi-cured thermosetting film on the both sides of the printed circuit board; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film, the solder resist mask pattern having been previously designed prior to irradiating.

2. (Canceled)

3. (Original) The method for forming a solder resist pattern according to claim 1, further comprising curing the semi-cured thermosetting film after laminating the thermosetting film.

4. (Previously presented) A method for forming a solder resist pattern comprising the steps of:

pre-treating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated by buildup process;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film.

5. (Original) The method for forming a solder resist pattern according to claim 4, wherein the pretreatment includes scrubbing.

6. (Previously presented) The method for forming a solder resist pattern according to claim 5, further comprising curing the thermosetting film after laminating the thermosetting film.

7. (Previously presented) A method for forming a solder resist pattern comprising the steps of:

pre-treating a portion exposed from a plurality of layers constituting a multilayer printed circuit board fabricated in a parallel manner;

laminating a thermosetting film on the pretreated portion; and

irradiating a laser beam to the laminated thermosetting film according to a solder resist mask pattern to selectively remove the thermosetting film.

8. (Original) The method for forming a solder resist pattern according to claim 7, wherein the pre-treatment includes scrubbing.

9. (Previously presented) The method for forming a solder resist pattern according to claim 8, further comprising curing the thermosetting film after laminating the thermosetting film.

10. (Previously presented) The method of claim 1, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

11. (Previously presented) The method of claim 4, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

12. (Previously presented) The method of claim 7, wherein the laser is a yttrium aluminum garnet laser, excimer laser, or carbon dioxide laser.

13. (Previously presented) A method for forming a solder resist pattern, comprising:
pre-treating both sides of a double-sided printed circuit board to provide pre-treated sides
of a printed circuit board;

applying a semi-cured thermosetting film on the pre-treated sides of the printed circuit
board to provide a thermoset film on the printed circuit board; and

irradiating a laser beam on the thermoset film to selectively remove the thermoset film to
provide a solder resist pattern.

14. (Previously presented) The method of claim 13, wherein pre-treating includes
scrubbing.

15. (Previously presented) The method of claim 13, further comprising curing the
thermosetting film.

16. (Previously presented) A method for forming a solder resist pattern comprising:
pre-treating a portion exposed from a plurality of layers, constituting a multi-layer printed
circuit board fabricated by a buildup process to provide a pre-treated portion;

laminating a thermosetting film on the pre-treated portion to provide a thermoset film;
and

irradiating a laser beam on the thermoset film to selectively remove the film to provide a
solder resist pattern.

17. (Previously presented) The method of claim 16, wherein pre-treating includes
scrubbing.

18. (Previously presented) the method of claim 16, further comprising curing the
thermosetting film.

19. (Previously presented) A method for forming a solder resist pattern, comprising:
pre-treating a portion exposed from a plurality of layers constituting a multi-layer printed circuit board fabricated in a parallel manner to provide a pre-treated portion;
laminating a thermosetting film on the pre-treated portion to provide a thermoset film;
and
irradiating a laser beam on the thermoset film to selectively remove the thermoset film to provide a solder resist pattern.
20. (Previously presented) The method of claim 19, wherein pre-treating includes scrubbing.
21. (Previously presented) The method of claim 19, further comprising curing the thermosetting film.
22. (New) A method for forming a solder resist pattern, comprising:
obtaining a substrate with an exposed circuit pattern on the surface thereof;
treating the substrate and the exposed circuit pattern to provide a treated circuit pattern;
applying a thermosetting film to the substrate to cover the exposed and treated circuit pattern to provide a thermosetting film as the outermost layer; and
removing the thermosetting film in selected areas with a laser beam to produce a substrate having a solder resist mask pattern.
23. (New) The method of Claim 22, comprising obtaining two of the substrates having a solder resist mask and placing one or more insulating layers between said two substrates so that the solder resist mask patterns of said two substrates are the outermost layers, then pressing the two substrates and one or more insulating layers to fabricate a multi-layer printed circuit board.

24. (New) The method of Claim 22, wherein the substrate comprises a double-sided printed circuit board having circuit patterns on both outermost sides of the printed circuit board and the thermosetting film is applied to cover the circuit patterns on both outermost surfaces and the thermosetting film on both sides is irradiated with a laser beam to provide a solder resist mask pattern on both outermost sides of the double-sided printed circuit board.